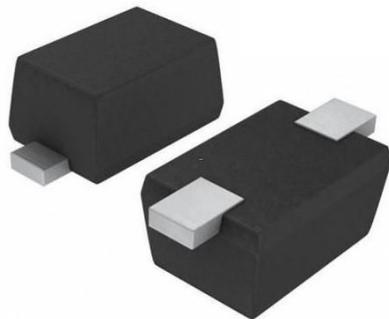


## Features

- 100Watts peak pulse power ( $t_p = 8/20\mu s$ )
- Bidirectional configurations
- Solid-state silicon-avalanche technology
- Low clamping voltage
- Low leakage current
- IEC 61000-4-2  $\pm 25kV$  contact  $\pm 25kV$  air
- IEC 61000-4-4 (EFT) 40A(5/50ns)
- IEC 61000-4-5 (Lightning) 10A(8/20 $\mu s$ )



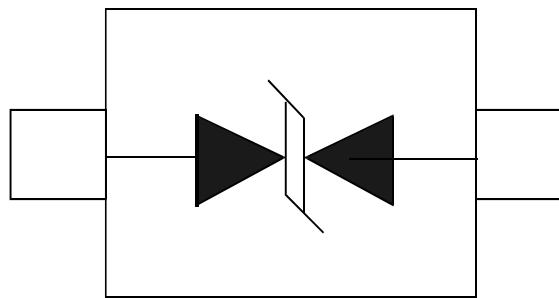
## Applications

- Microprocessor based equipment
- Personal Digital Assistants (PDA's)
- Notebooks, Desktops, and Servers
- Portable Instrumentation
- Pagers Peripherals

## Mechanical Data

- SOD523 package
- Molding compound flammability rating: UL 94V-0
- Packaging: Tape and Reel
- RoHS/WEEE Compliant

## Schematic & PIN Configuration



SOD-523

## Absolute Maximum Rating

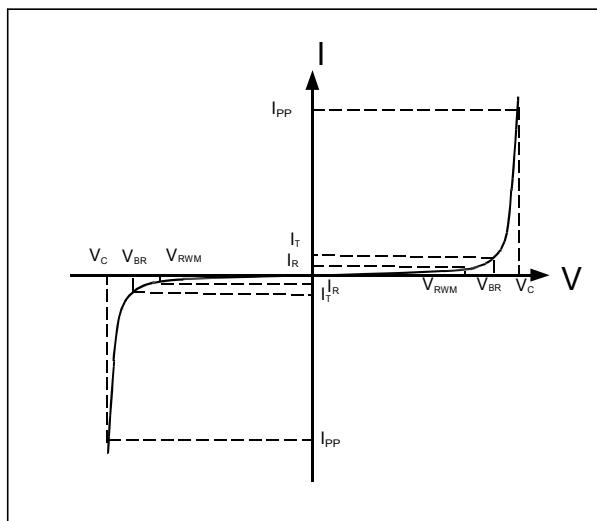
Rating	Symbol	Value	Units
Peak Pulse Power ( $t_p = 8/20\mu s$ )	$P_{PP}$	100	Watts
Peak Pulse Current ( $t_p = 8/20\mu s$ )(note1)	$I_{pp}$	10	A
ESD per IEC 61000-4-2(Air) ESD per IEC 61000-4-2(Contact)	$V_{ESD}$	25 25	kV
Lead Soldering Temperature	$T_L$	260(10seconds)	°C
Junction Temperature	$T_J$	-55 to + 150	°C
Storage Temperature	$T_{stg}$	-55 to + 150	°C

## Electrical Characteristics

Parameter	Symbol	Conditions	Min	Typical	Max	Units
Reverse Stand-Off Voltage	$V_{RWM}$				3.3	V
Reverse Breakdown Voltage	$V_{BR}$	$I_T = 1mA$	3.8	4.3	5.3	V
Reverse Leakage Current	$I_R$	$V_{RWM} = 5.0V, T = 25°C$			500	uA
Clamping Voltage	$V_C$	$I_{PP} = 10A, t_p = 8/20\mu s$		8	10	V
Junction Capacitance	$C_j$	$V_R = 0V, f = 1MHz$		12	15	pF

## Electrical Parameters (TA = 25°C unless otherwise noted)

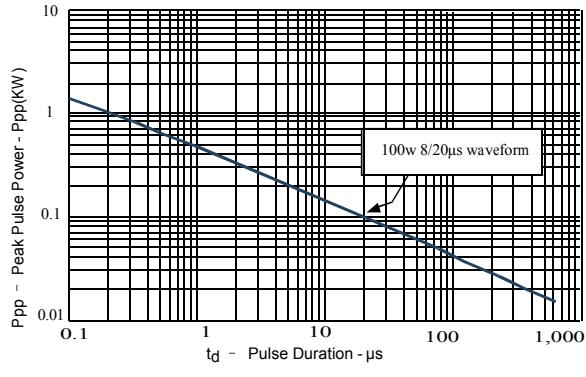
Symbol	Parameter
$I_{PP}$	Maximum Reverse Peak Pulse Current
$V_C$	Clamping Voltage @ $I_{PP}$
$V_{RWM}$	Working Peak Reverse Voltage
$I_R$	Maximum Reverse Leakage Current @ $V_{RWM}$
$V_{BR}$	Breakdown Voltage @ $I_T$
$I_T$	Test Current



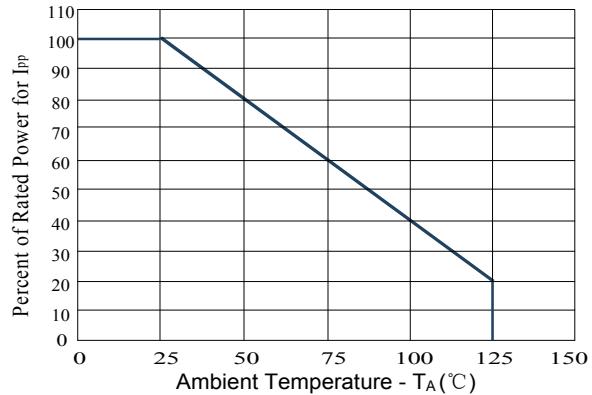
Note: 8/20μs pulsed waveform.

## Typical Characteristics

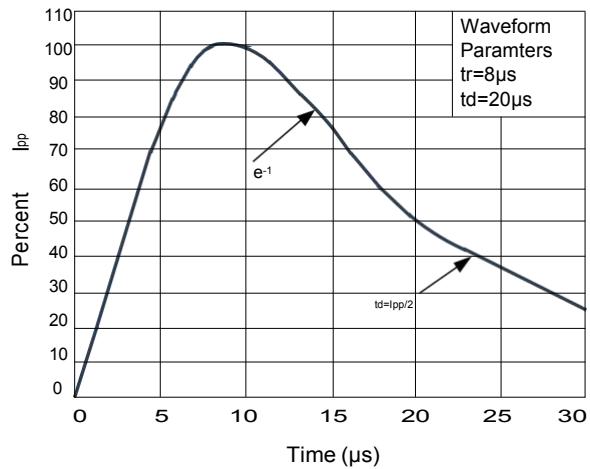
**Figure 1: Peak Pulse Power vs. Pulse Time**



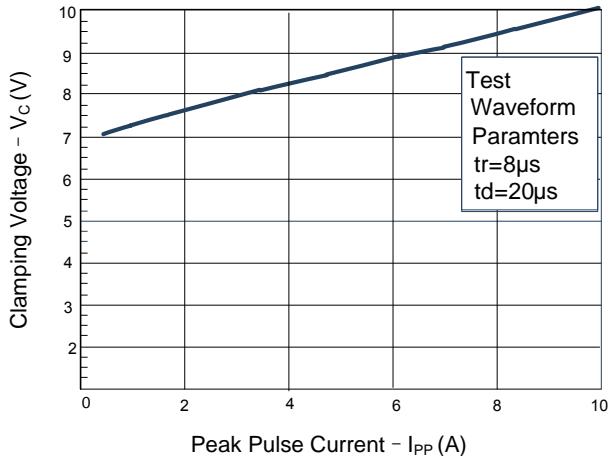
**Figure 2: Power Derating Curve**



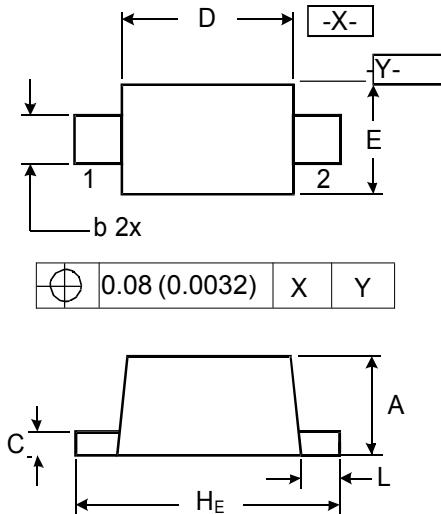
**Figure 3: Pulse Waveform**



**Figure 4: Clamping Voltage vs.Ipp**



## Outline Drawing – SOD523



**DIMENSIONS**

SYMBOL	MILLIMETER		INCHES	
	MIN	MAX	MIN	MAX
A	0.50	0.70	0.020	0.028
b	0.25	0.35	0.010	0.014
C	0.07	0.20	0.0028	0.0079
D	1.10	1.30	0.043	0.051
E	0.70	0.90	0.028	0.035
H <sub>E</sub>	1.50	1.70	0.059	0.067
L	0.15	0.25	0.006	0.010

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